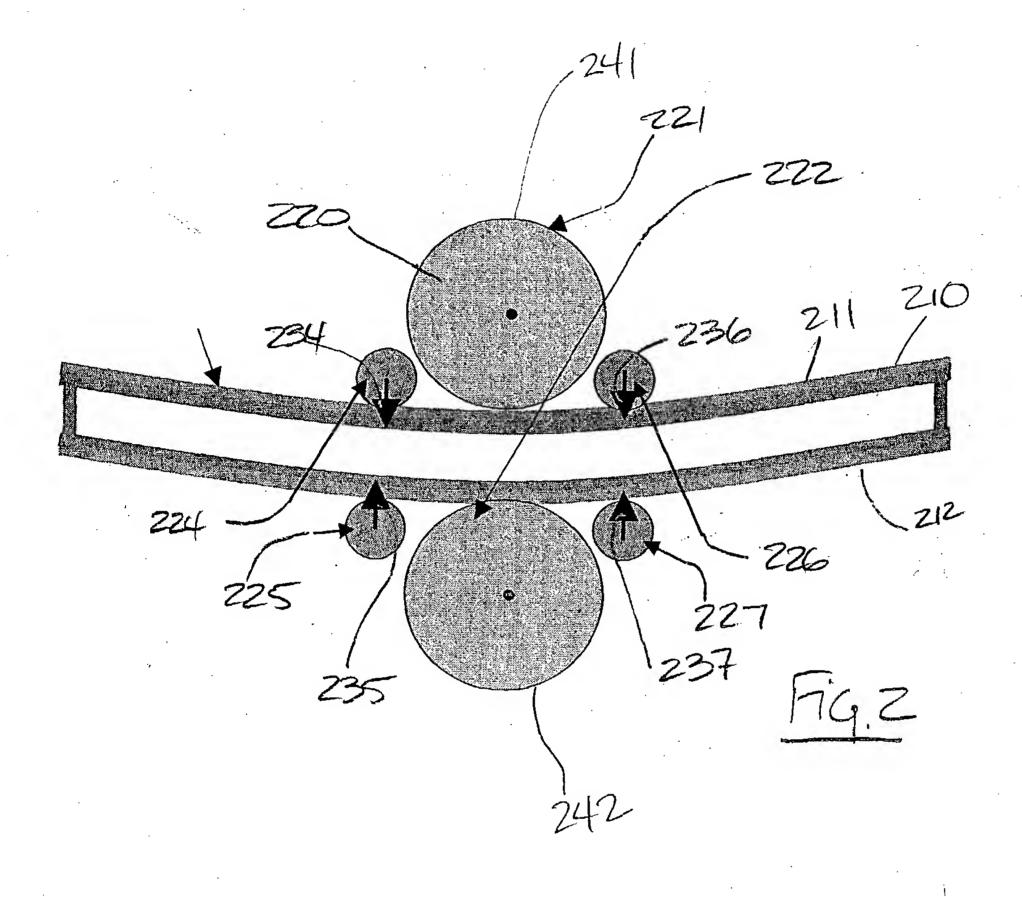


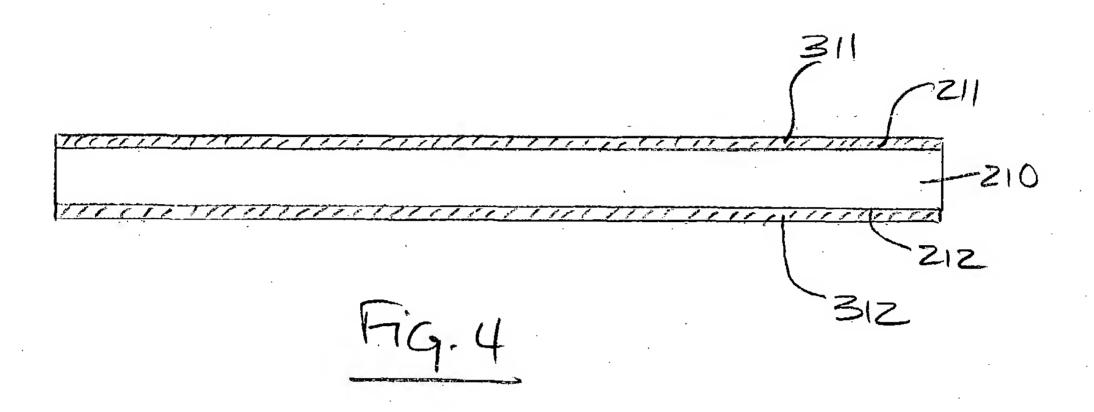
Fig.1

•



211 -211 -210

Fig. 3



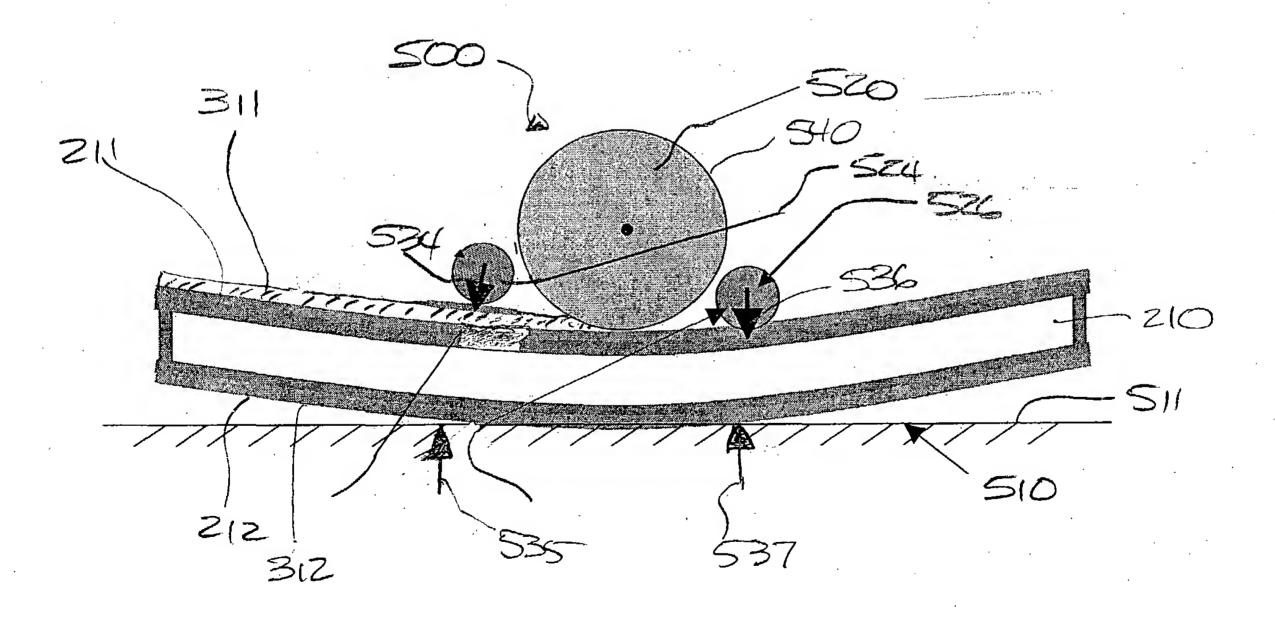
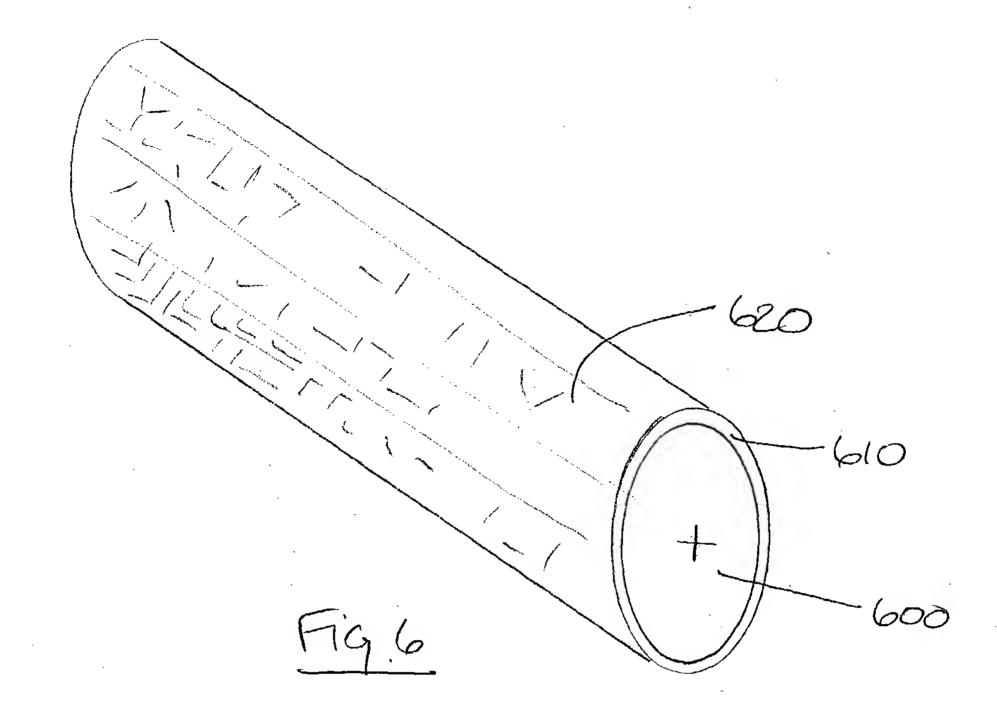
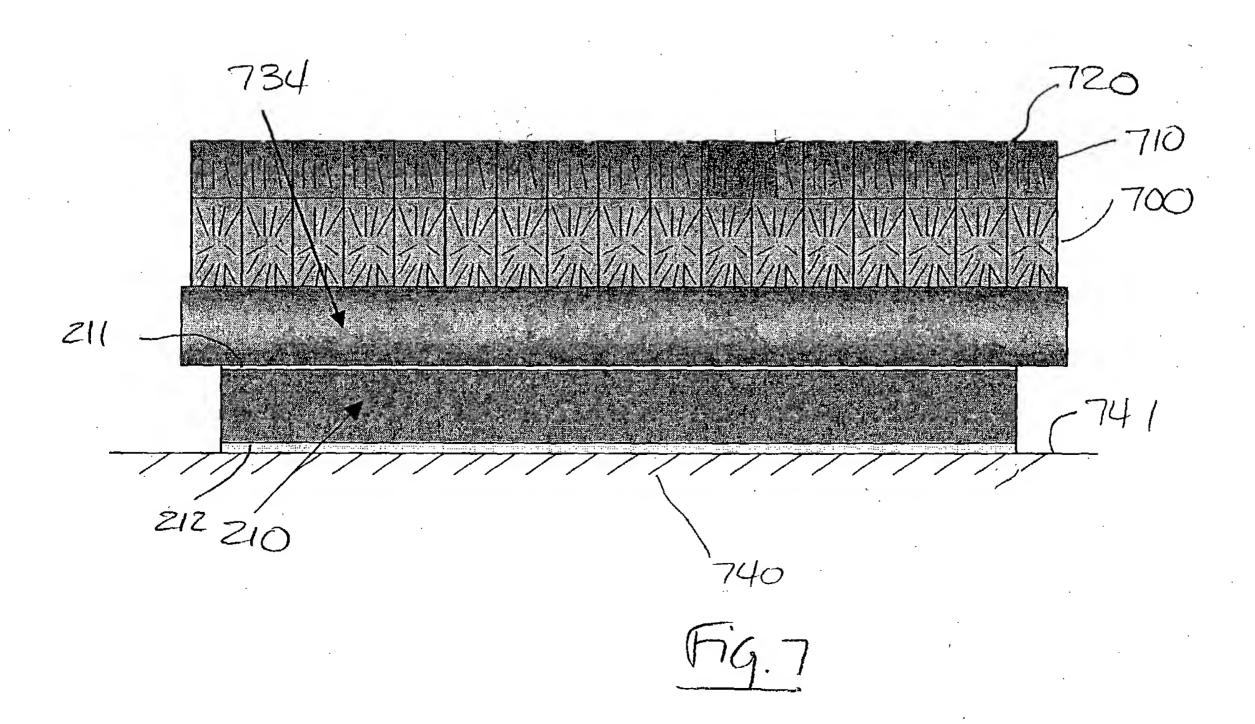
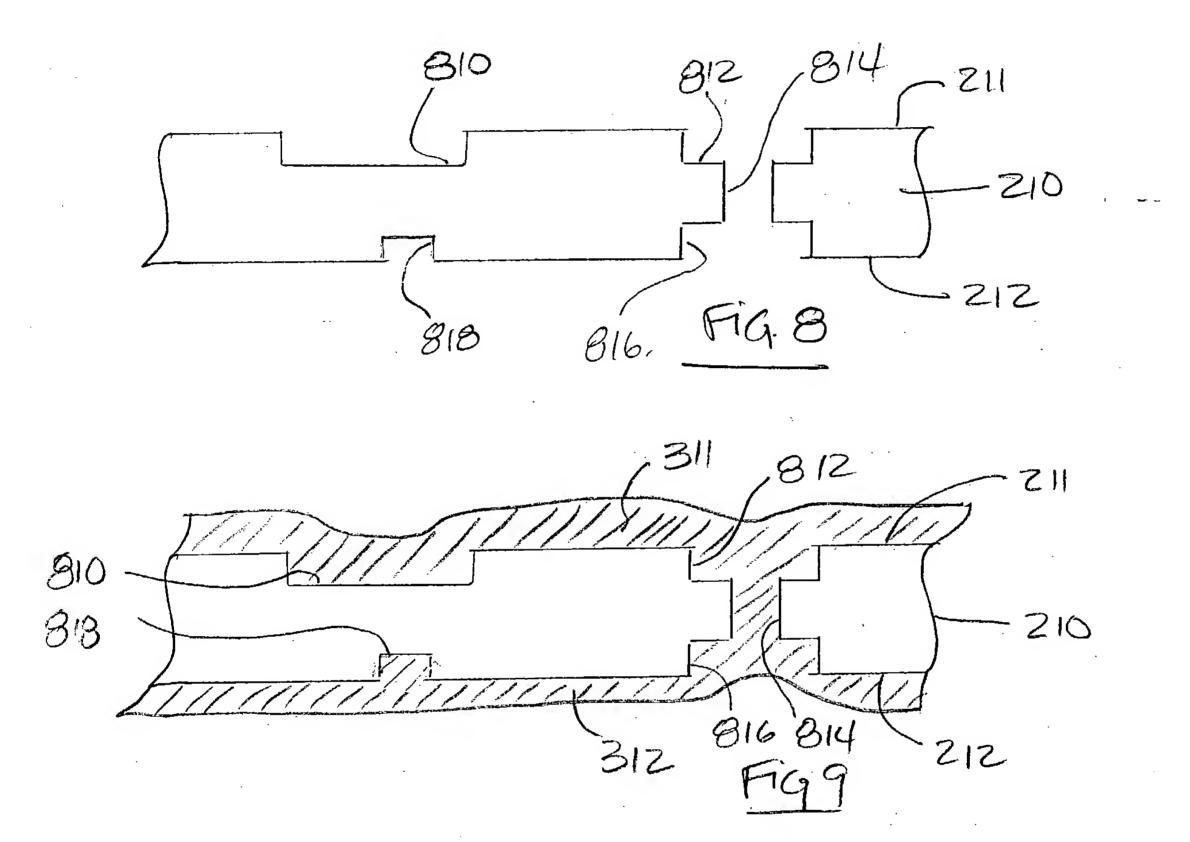
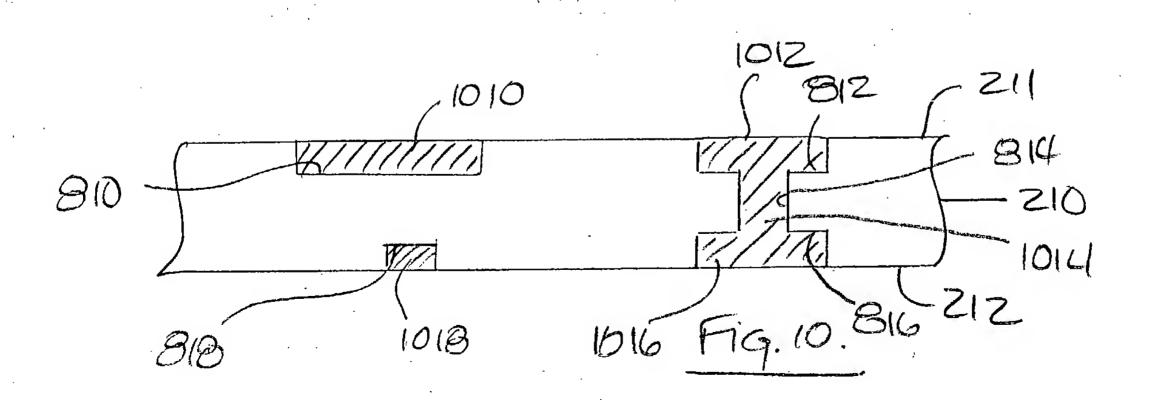


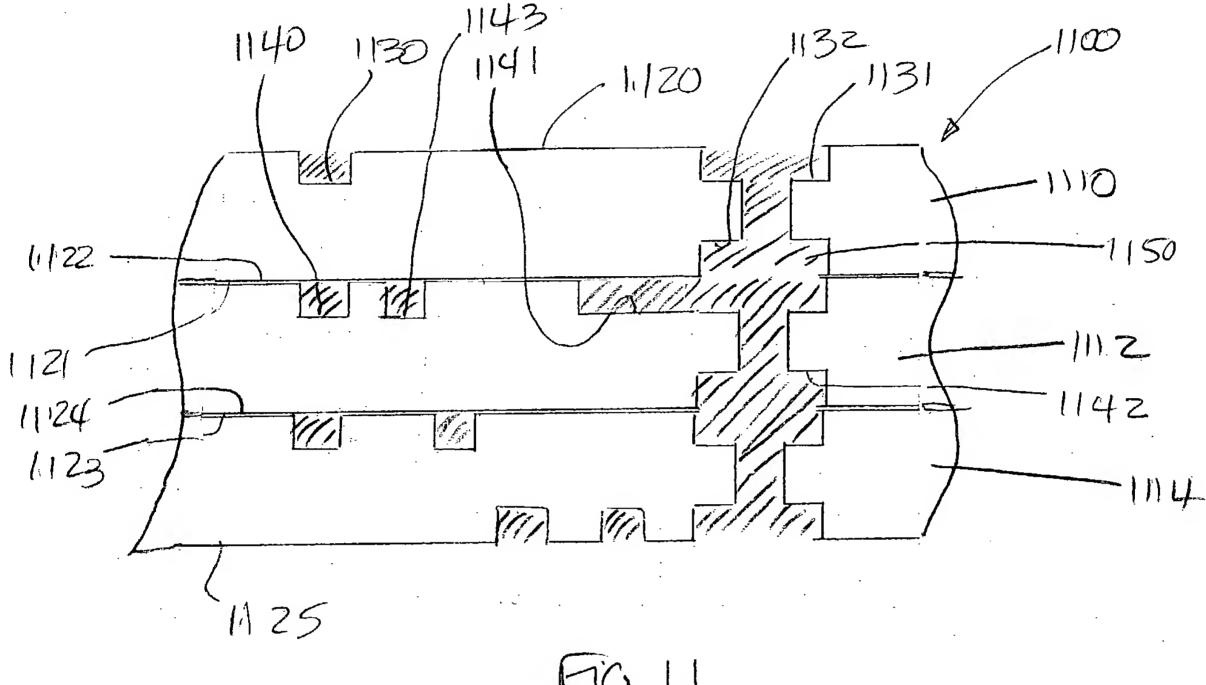
Fig. 5











MG.11

1200

210

indent a major surface of a substrate with a plurality of features

1212

plate the major surface and the indentations formed with a conductive layer

1214

remove a portion of the conductive layer leaving at least one of the plurality of the indentations filled with conductive material separated from at least one other of the plurality of the indentations filled with conductive material separated by nonconductive material

F19.12

1310 indent a first major surface of a first substrate with a first plurality of features indent a second major surface of a first substrate with a second plurality of features plate the first major surface and the indentations formed in the first major surface with a conductive layer plate the second major surface and the indentations formed in the second major surface with a conductive layer remove a portion of the conductive layer on the first major surface leaving at least one of the plurality of the indentations in the first major surface filled with conductive material separated from at least one other of the plurality of the indentations in the first major surface filled with conductive material separated by non-conductive material remove a portion of the conductive layer on the second major surface leaving at

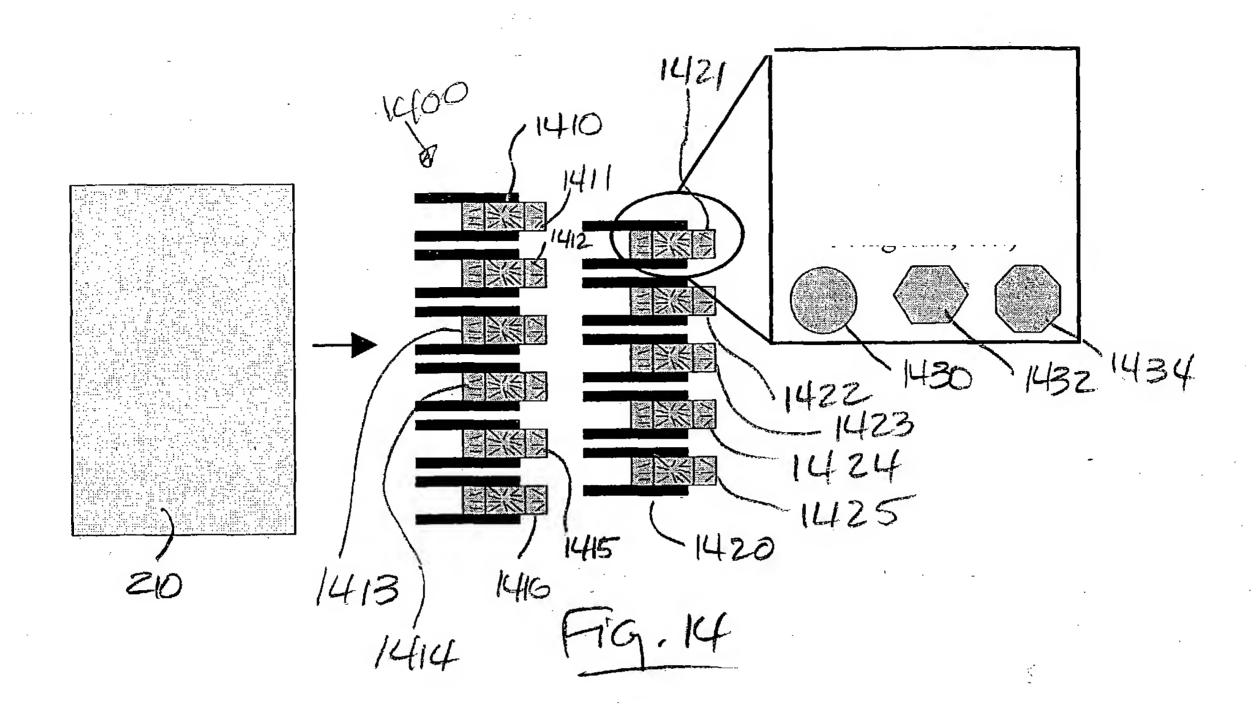
least one of the plurality of the indentations in the second major surface filled with

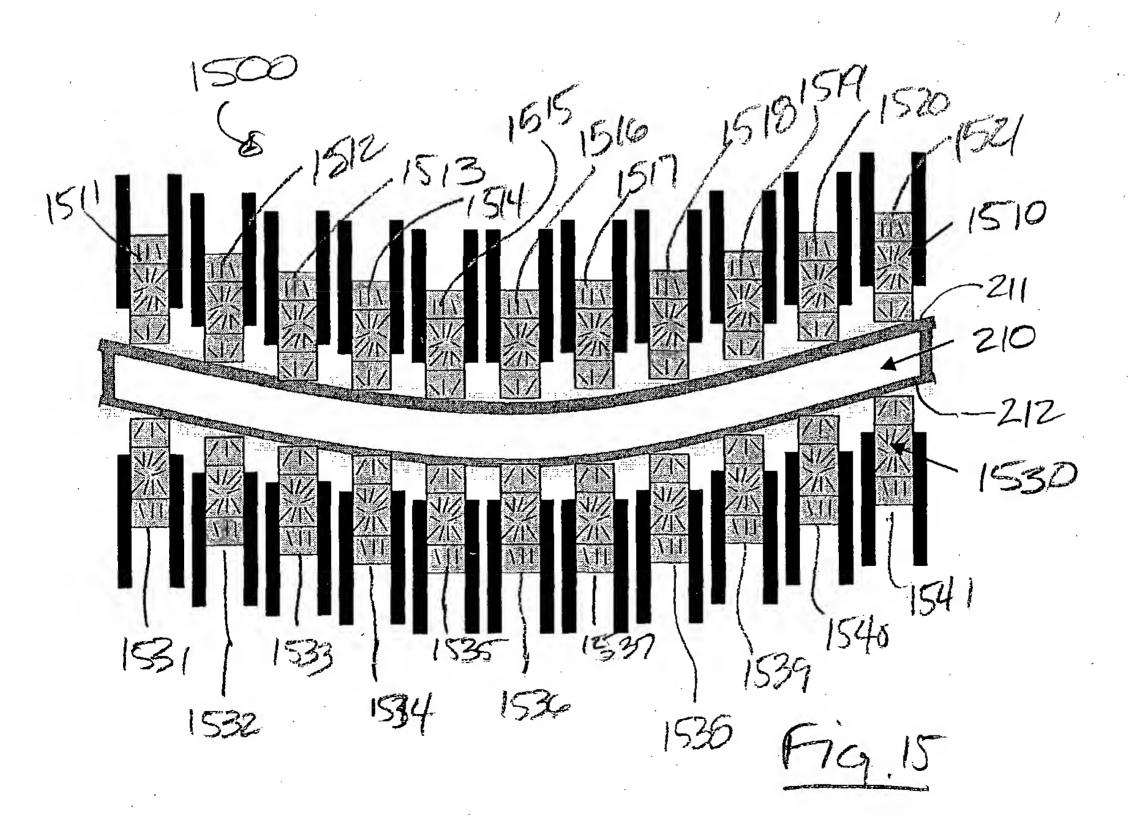
material

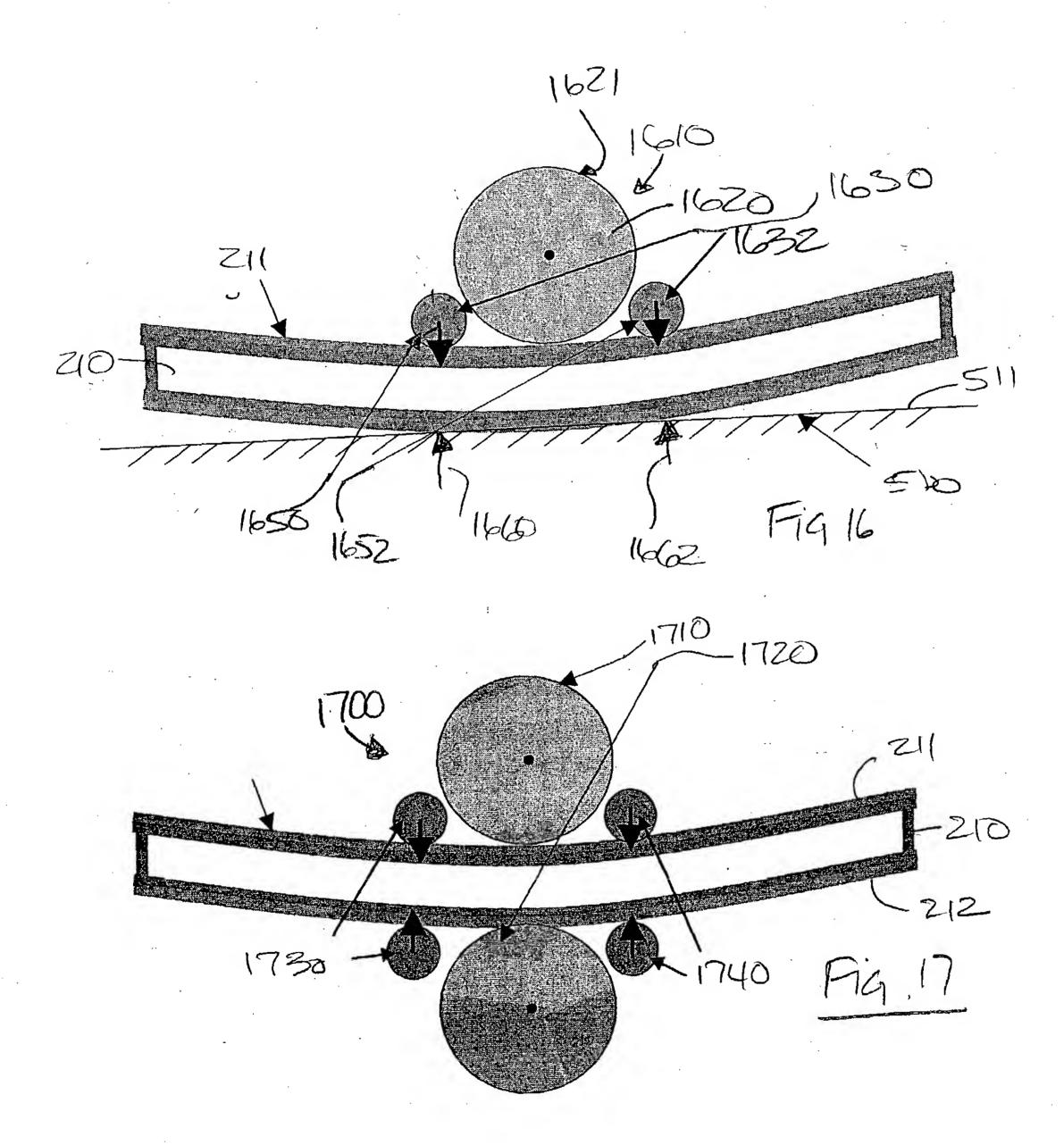
conductive material separated from at least one other of the plurality of the indentations

in the second major surface filled with conductive material separated by non-conductive

Fig. 13







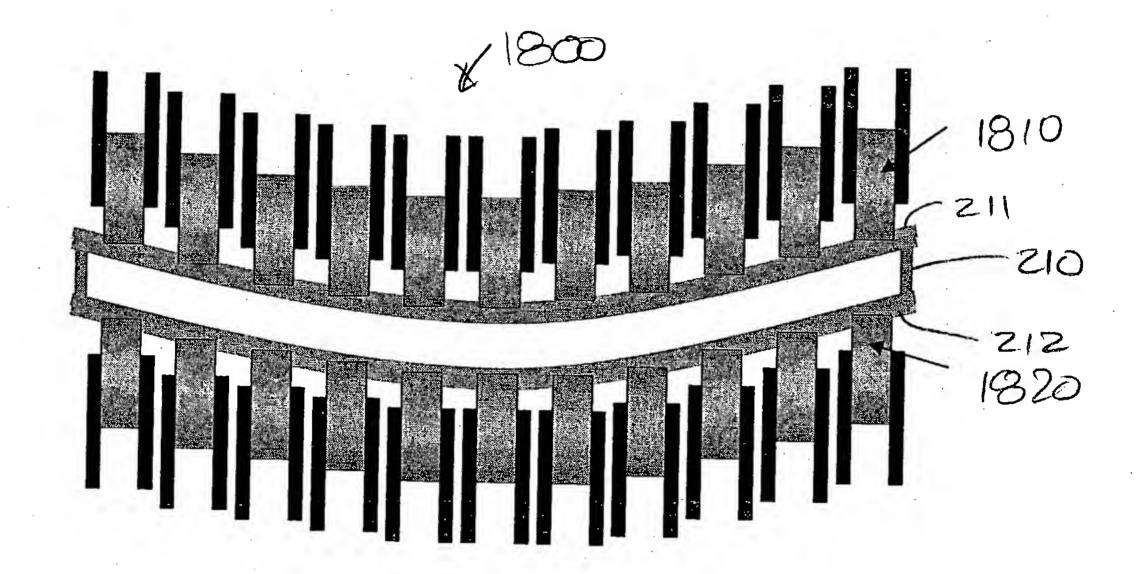


Fig. 18

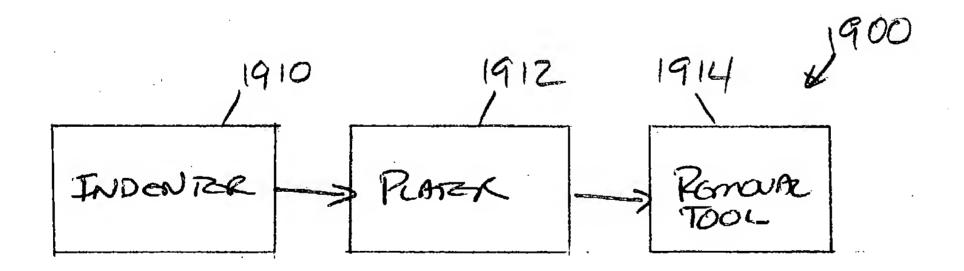


Fig. 19

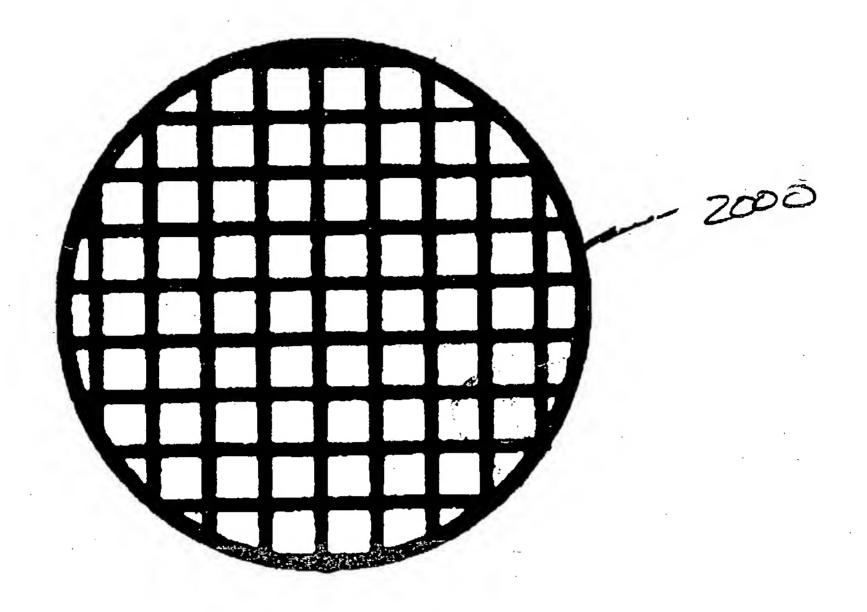


Fig. 20

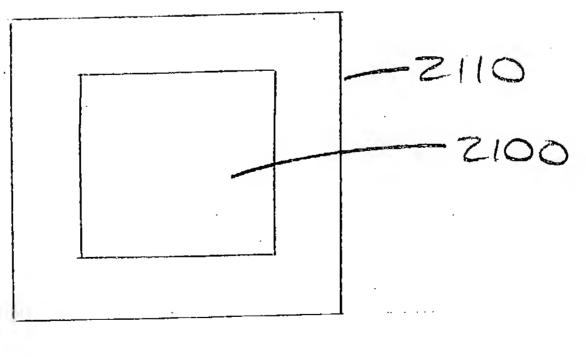


Fig 21